

## LTM4609-BGA 141LD 15mm X 15mm X 3.42mm (TABLE OF MATERIAL DECLARATION)

*The LTM4609 is RoHS compliant per EU RoHS Directive 2003/95/EC.*

It contains less than 100ppm cadmium (Cd) and less than 1,000ppm of each - lead (Pb), mercury (Hg), hexavalent chromium (Cr+), polybrominated biphenyl (PBB) and polybrominated diphenyl ether (PBDE)

No.	Part Name	Material Name	Component Weight (gram)	Materials Analysis (element)	CAS Number	Material Mass (gram)	Materials Analysis (weight %)
1	Substrate	Circuit Board	0.1453	Barium Compounds	7727-43-7	0.00218	1.500
				Filler Substances (Silica Crystalline)	non-disclosure	0.05801	39.915
				Copper Metal	7440-50-8	0.08138	56.000
				Copper Compounds	1328-53-6	0.00003	0.018
				Ecotoxic substances	7439-92-1	0.00000	0.000
				Gold metal or alloy	7440-57-5	0.00067	0.460
				Nickel	7440-02-0	0.00305	2.100
				Zinc	7440-66-6	0.00001	0.007
2	Solder Ball	Alloy	0.26794	Tin (Sn)	7440-31-5	0.25856	96.500
				Silver (Ag)	7440-22-4	0.00804	3.000
				Copper (Cu)	7440-50-8	0.00134	0.500
3	Solder Paste	Alloy	0.0216	Sn	7440-31-5	0.02049	95.000
				Sb	7440-36-0	0.00108	5.000
4	Passive/Active Components		0.1331	Nickel	7440-02-0	0.01009	7.579
				Tin (Sn)	7440-31-5	0.00316	2.371
				Copper (Cu)	7440-50-8	0.03931	29.529
				Ceramic	12047-27-7	0.08017	60.221
				glass	1317-36-8	0.00027	0.199
				Epoxy	non-disclosure	0.00013	0.101
5	Active lcs	Silicon	0.0183	Silicon	7440-21-3	0.01829	100.000
6	Wire	Gold	0.0029	Au	7440-57-5	0.00294	99.990
8	Encapsulation	Epoxy Resin	1.1702	Fused Silica	60676-86-0	0.89643	76.607
				Epoxy Resin	non-disclosure	0.11233	9.600
				Phenol Resin	non-disclosure	0.10335	8.832
				Crytalline Silica	14808-60-7	0.03484	2.977
				Carbon Black	1333-86-4	0.00581	0.497
				Metal Hydroxide	non-disclosure	0.01742	1.489
Total Package Weight			1.7593				

Note: Composition derived from MSDS and material C of C from Vendors  
Component Weight based on assembly of generic parts